



Correct as of 06-May-2024 9:05pm For the latest version of our agenda, visit csinternational.net

Day 1 - Monday 15th April 2024

18:30 Pre-conference networking drinks reception

Day 2 - Tuesday 16th April 2024

08:00

Registration and welcome refreshments 08:50 Housekeeping by Chris Meadows and Tim Bettles - Conference Chairs Ensuring SiC's phenomenal success Silicon Carbide: a game changer in power electronics 09:00 Presented by Mario Saggio - STMicroelectronics Supporting SiC Success Stories Through Technical Innovation 09:15 Presented by David Liese - htt Group, and Michael Köppl - htt Group Next-Generation Factory Inspection: Improving Performance by Synthesizing Intelligent Microscopy 09:30 Presented by Marius Fischer - Nanotronics Challenges in HVM Amidst Evolving Device Architectures and Requirements for Compound Semiconductor based Power 09:45 Devices Presented by Nick Keller - Onto Innovation Sharpening SiC Wafer specs and Frontend Performance by Crystal Orientation Metrology 10:00 Presented by Lars Grieger - Malvern Panalytical Sample preparation and TEM imaging techniques for advanced power device analysis 10:15 Presented by Antonio Mani - Thermo Fisher Scientific 10:30 Morning Break Giving SiC a superjunction 11:10 Presented by Reza Ghandi - GE Aerospace The Unspoken Impacts of SiC Power Packaging 11:25 Presented by Kevin Speer - Microchip Challenges and solutions in new generation SiC metrology 11:40 Presented by Dr. Eszter Najbauer - Semilab Accelerating semiconductor technologies for the green revolution 11:55 Presented by Shiva Rai - Applied Materials A Hybrid Defect Inspection System for SiC substrate and Epi applications 12:10 Presented by Aris Ma - AK Optics Technology Co. Ltd Capital Efficient Systems for SiC Manufacturing Expansion and R&D 12:25 Presented by Brian Stickney - C & D Semiconductor 12:40 Lunch Break Enabling Low Cost SiC Boule Fabrication - The BoulePro 200AX is the New Process Of Record 13:55 Presented by Jeff Gum - Usach Industry ready detection of TSDs and BPDs in SiC wafers 14:10 Presented by Dr.-Ing. Christian Reimann - Rigaku Cutting-edge SiC Manufacturing: Beyond Chemical-Mechanical Constraints 14:25 Presented by Philipp Böttger - scia Systems GmbH Modernizing Industrial Low Voltage Motor Drives with Silicon Carbide 14:40 Presented by Pranjal Srivastava - Wolfspeed PulseForge and Teikoku Taping Systems Announce Novel Fully Automated Photonic Debonding Platform 14:55 Presented by Vahid Akhavan - PulseForge (in association with Teikoku Taping Systems Inc) Coating at its best - Spraying graphite parts with tantalum carbide cuts the cost of producing SiC crystals 15:10 Presented by Dr.-Ing. Matthias Trempa - Fraunhofer IISB Powering the SiC Revolution with Vertical Integration 15:25 Presented by Ajay Poonial Pai - Sanan 15:40 Afternoon Break Taking power from the photon Record-breaking solar cells 16:20 Presented by Dr. Oliver Höhn - Fraunhofer ISE Integrated storage unlocks CPV's full potential 16:35 Presented by Kira Rundel - RayGen Germanium Substrates for Photonics and PV: Ensuring Supply Security, Advancing Recycling and Enabling CMOS integration 16:50 Presented by Ivan Zyulkov - Umicore Lattice-matched III-V solar cells. Progress and application opportunities 17:05 Presented by Prof. Mircea Guina - Tampere University

New frontiers for the LED

17:20	Development of far-UVC LEDs for sensing and skin tolerant antisepsis Presented by Sven Einfeldt - FBH Berlin		
17:35	Heterogenous Integration of Compound Semiconductors by W2W and D2W Bonding Presented by Dr. Bernd Dielacher - EV Group		
17:50	Making monolithic RGB displays with InGaN Presented by WonTaeg Lim - Soft-Epi		
18:05	Closing Remarks		
18:10	Networking Drinks / Dinner Reception		

Day 3 - Wednesday 17th April 2024

08:00 Registration and welcome refreshments 08:50 Housekeeping by Chris Meadows and Tim Bettles - Conference Chairs Accelerating the growth of GaN Sponsored by Precision Fabricators Where will GaN Power Semiconductors find their greatest success in the 2020s? 09:00 Presented by Richard Eden - Omdia The strengths of IC enhancement-mode GaN 09:15 Presented by Andrea Bricconi - Cambridge GaN Devices 09:30 Presentation Title to be Confirmed Harnessing the Power of RF GaN-on-Si Technology for Next Generation Connectivity 09:45 Presented by Nadine Collaert - imec Accelerating the Growth of GaN-based Power Electronics Via Adoption of 300mm Technology 10:00 Presented by Rudy Parekh - Veeco Next Level Epitaxy: Revolutionizing Mass Production of Wide Bandgap Semiconductors 10:15 Presented by Dr. Yilmaz Dikme 10:30 Morning Break Considerations for Tool-To-Tool Matching Across a Fleet of Metrology Tools 11:10 Presented by Tamzin Lafford - Bruker UK Connected metrology - Full 2D characterization of HEMT device structure epi-wafers 11:25 Presented by Johannes Zettler - LayTec AG **Emerging Growth Opportunities for MBE in GaN** 11:40 Presented by Brian Miller - Riber Commercialization of buffer-free GaN on SiC materials for defense, space, telecom markets and beyond 11:55 Presented by Jr-Tai Chen - SweGaN Numerical design propels RF and power GaN technology 12:10 Presented by Ahmed Nejim - Silvaco Solving the EMC and thermal issues of driving GaN at high speed 12:25 Presented by Rupert Baines - QPT GaN: Delivering on the Net-Zero Economics of an Al-Enabled Future 12:40 Presented by Peter Rabbeni - IQE 12:55 Lunch Break **Expanding horizons for surface emitters** VCSELs: Driving Innovations in 3D Sensing and Data Communication 14:10 Presented by Ali Jaffal - Yole Group Vertilas InP VCSELs to address fast growing and novel applications at and beyond 1.3 I m 14:25 Presented by Christian Neumeyr - Vertilas Expanding the scope of VCSELs through wavelength extension, added functionality and high power density 14:40 Presented by Julien Boucart - Coherent Speeding VCSEL feedback 14:55 Presented by Jack Baker - ICS Building, powerful, blue-surface-emitting SLEDs 15:10 Presented by Juan Morales - iSLight Novel high-power VCSEL laser modules for Battery Manufacturing 15:25 Presented by Roman Koerner - TRUMPF Placing photonic crystal nano-lasers to silicon 15:40 Presented by Mingchu Tang - University College London 15:55 **Closing Remarks**



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